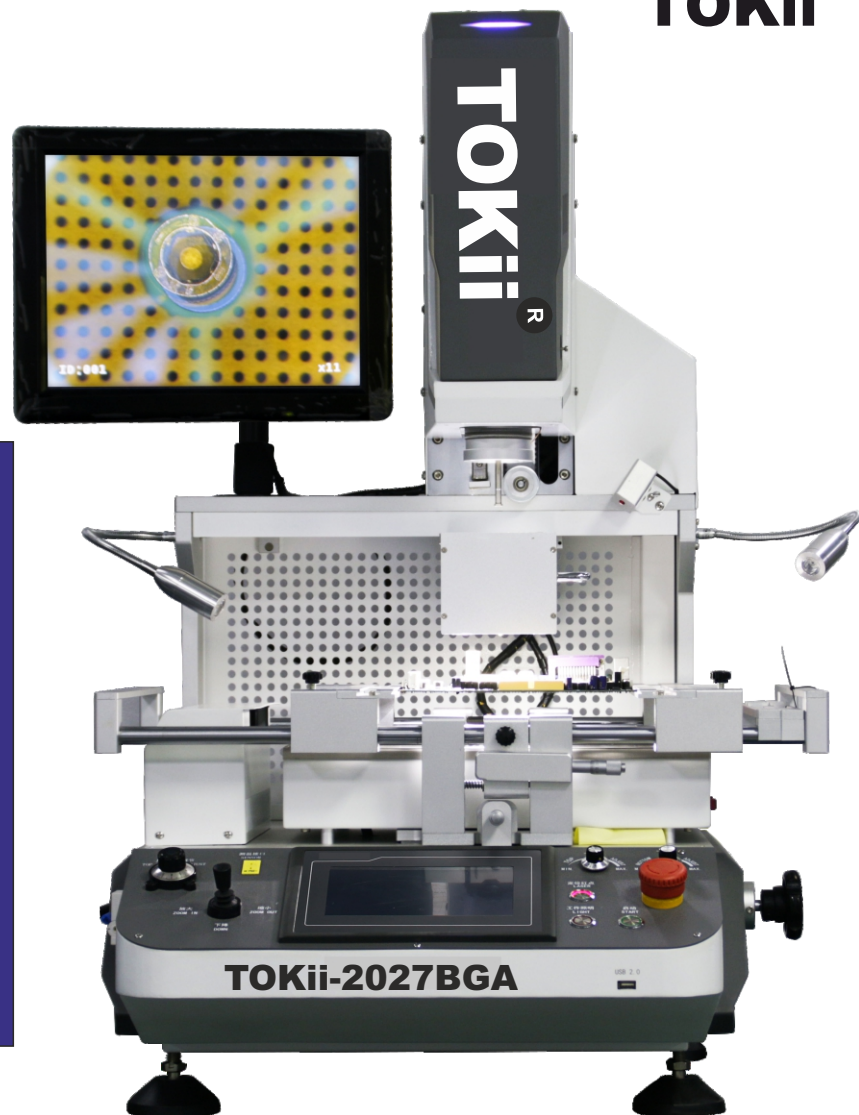


TOKii-2027BGA

- FOR SMD BGA/QFP/QFN/CSP/SOP
- OPTICAL ALIGNMENT
- TEMP PROFILE DISPLAY
- JOYSTICK FOR EASY ALIGNMENT
- LASER FOR CENTER POINT
- AUTOMATIC PICK
- MOUNT PRESSURE CONTROL
- 3 HEATER - TOP, BOTTOM AND PRE HEATER
- TEMP. ACCURACY $\pm 1^{\circ}\text{C}$
- 50 GROUP PROFILE CAN BE SAVED



FEATURE

- Optical Alignment Rework Equipment
- Real-time Temperature Monitoring
- Real-time temperature display, with automatic curve analysis function.
- Optical Alignment System High-definition CCD (2M pixels) digital imaging, automatic optical zoom system, manual control and laser red-dot alignment
- Rapid Heating and Cooling
- The IR preheating zone is heated by a medium wave ceramic infrared heating plate,
- A multi-functional movable PCB fixing bracket and a BGA bottom support frame.
- Laminar integrated cooling fan.
- Rework micro BGA, VGA, CCGA, QFN, CSP, LGA, SMD, etc
- Large area of infrared carbon fiber Pre-heating system, with the advantage of pre-heating fast and evenly and no light pollution.
- Temperature parameters protected by limits of authority, for avoiding error settings.
- Hot air flow can be adjustable to meet the demand of any chips
- Laser positioning available, to make the positioning faster.

- Superior safety functions :After desoldering and soldering, there is alarming. when temperature goes out of control. The circuit will automatically power off, it is of double over-temperature protection function. Temperature parameter has a password to avoid from arbitrary changes, with superior safety protection functions, can protect PCB board components and the machine from damage at any abnormal situation.

SPECIFICATIONS

Model No.	TOKii-2027BGA
Power Supply	AC220V ±10% 50/60Hz
Power	Power 5.65KW(Max} Top heater(1.45KW} Bottom heater(1.2KW) IR Preheater(2.7KW)
PCB Size	412x370mm(Max) ;6x6mm(Min)
BGA Chip Size	60x60mm(Max} & 2x2mm(Min)
IR Temp.Zone Size	285 x 375 mm
External Temperature Sensor	1PCS
Operation Method	7' HD touch screen
Control System	Autonomous heating control system V2(with software copyright)
Display System	15" industrialdisplay(720P front screen)
Alignment System	2M pixels SD digital imaging system,automatic optical zoom with laser red-dot indicator
Vacuum adsorption	Automatic
Alignment Accuracy	± 0.02mm
Temp.Control	K-type thermocouple closed-loop control with accuracy up to ±3°C
Feeding Device	No
Positioning	V-groove with universal fixture
Dimensions	L685xW633xH850mm
Weight	76KG

Each unit consist

- TOKii-2027 BGA Rework Station1 pcs,
- PCB Fixture 6 pcs
- M5*30 Supporting Screw 6 pcs
- Handle Screw 6 pcs
- Temperature sensor 1pcs
- Vacuum sucker 12pcs
- Heaters 2 pcs
- K type thermocouple wire1 pcs
- Nozzle 31*31mm 1pcs
- Nozzle 10*10 mm 1pcs
- Nozzle 41*41 mm 1pcs
- Nozzle 20*20 mm 1pcs
- Bottom Nozzle 35*35mm 1pcs
- Flux Brush 1 pcs
- LCD monitor 1 Pcs
- Manual1 pcs